



Material Content Data Sheet



Sales Product Name		ICE2A365		Issued		29. August 2013			
MA#		MA001118732							
Package		PG-DIP-8-13		Weight*		558.46 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	9.187	1.65	1.65	16451	16451	
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96		
	non noble metal	zinc	7440-66-6	0.215	0.04		385		
	non noble metal	iron	7439-89-6	4.297	0.77		7694		
wire	non noble metal	copper	7440-50-8	174.475	31.24	32.06	312421	320596	
	noble metal	gold	7440-57-5	0.179	0.03	0.03	321	321	
	encapsulation	organic material	carbon black	1333-86-4	1.076	0.19		1927	
plastics	plastics	epoxy resin	-	34.792	6.23		62300		
	inorganic material	silicondioxide	60676-86-0	322.815	57.81	64.23	578044	642271	
leadfinish	non noble metal	tin	7440-31-5	7.496	1.34	1.34	13422	13422	
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1425	1425	
glue	plastics	epoxy resin	-	0.462	0.08		827		
	noble metal	silver	7440-22-4	2.618	0.47	0.55	4687	5514	
*deviation	< 10%				Sum in total:		100,00		1000000

Important Remarks:

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